

2024 4th International Conference on Intelligent Technology and Embedded Systems

September 20-23, 2024
Chengdu, China



PROCEEDINGS

Accepted and registered full papers of ICITES 2024 will be published by ICITES Conference Proceedings

ICITES 2023| IEEE Xplore, Ei Compendex & Scopus Index
ICITES 2022| IEEE Xplore, Ei Compendex & Scopus Index
ICITES 2023| IEEE Xplore, Ei Compendex & Scopus Index

SCI / EI / Scopus Journals

Selected papers after extension will be recommended to the following journals:

Journal of Electronic Science and Technology

ISSN: 1674-862X

Citescore Track: 2.7

Indexing: Ei Compendex, Scopus, INSPEC, CSCD, DOAJ etc., OA on ScienceDirect.

Journal of Systems Architecture

ISSN: 1383-7621

Citescore Track: 7.3; Impact Factor: 5.836

Indexing: SCIE, Ei, Scopus, etc.

Journal of Circuits, Systems and Computers

ISSN: 0218-1266

Citescore Track: 2.6; Impact Factor: 1.278

Indexing: SCIE, Compendex, Scopus, etc.

Computer Systems Science and Engineering

ISSN: 0267-6192

Citescore Track: 1.9; Impact Factor: 4.397

Indexing: SCI, Scopus, ACM Digital Library

TOPICS

Track 1: Embedded Processor and System on Chip

Track 2: Modeling and Design Automation

Track 3: Safety, Security and Reliability

Track 4: Embedded Machine Learning

Track 5: Accelerators and Heterogeneous System

Track 6: Communication and Memory Subsystem

Track 7: Embedded Operating Systems and Middleware

Track 8: Real-time and Distributed Intelligent Systems

Track 9: Embedded System for IoT & Signal Processing

Track 10: Industrial Practices and Case Studies

Special Session

1 Intelligent and Embedded Computing for Electric Power Systems

2 AI and Embedded Systems for Computer Vision and Multimedia

3 Trustworthy AI for Embedded Applications

SUBMISSION

EasyChair <https://easychair.org/conferences/?conf=icites20240>

Submission Deadline: April 30th, 2024

Notification: May 30th, 2024

Registration Deadline: June 20th, 2024

CALL for PAPERS

ORGANIZING COMMITTEES

Advisory Committee

Xiaobo Sharon Hu, Notre Dame University

Zebo Peng, Linköping University

Shiyan Hu, University of Southampton

Bing Guo, Sichuan University

General Chairs

Wei Jiang, University of Electronic Science and Technology of China

Zonghua Gu, Umeå University

Tsung-Yi Ho, The Chinese University of Hong Kong

Technical Program Committee Chairs

Jinsun, Nanjing University of Science and Technology

Yang Liu, Sichuan University

Di Liu, Norwegian University of Science and Technology

Technical Program Committee Co-chairs

Qi Sun, Zhejiang University

Mengmeng Jing, University of Electronic Science and Technology of China

Angeliki Kritikakou, IRISA/INRIA and University of Rennes 1

Track Chairs

Yongli Wang, Nanjing University of Science and Technology

Weichen Liu, Nanyang Technological University

Biao Hu, China Agricultural University

Mohsen Imani, University of California- Irvine

Haojie Zhou, Jiangnan University

Ying Wang, Chinese Academy of Sciences

Lynda Boukela, Deutsches Elektronen-Synchrotron

Jiankang Ren, Dalian University of Technology

Lingzhong Meng, Chinese Academy of Sciences

Laha Ale, Southwest Jiaotong University

Special Session Chairs

Gang Chen, Sun Yat-sen University

Di Lin, University of Electronic Science and Technology of China

Dongdong Li, National University of Defense Technology

Zimeng Zhou, Shandong University

Local Chairs

Xupeng Wang, University of Electronic Science and Technology of China

Cheng Dai, Sichuan University

Zhengwei Chang, State Grid Sichuan Electric Power Research Institute

Publicity Chairs

Qiao Li, Xiamen University

Deepak Adhikari, University of Electronic Science and Technology of China

Junhuan Yang, George Mason University

Publication Chairs

Jinyu Zhan, University of Electronic Science and Technology of China

Peijin Cong, Nanjing University of Science and Technology

Liang Leng, Beijing Jiaotong University

Jing Luo, University of Electronic Science and Technology of China

Finance Chair

Zhoupeng Xu, Southwest Jiaotong University

CONTACT

Dr. Jenny Luo

E-mail: icites@163.com

Tel: 139-7222-2224

Co-sponsored by

Hosted by

Patrons

